



2015/3 Presentation

Note: This document is a translation of the 2015/3 Presentation written in Japanese. In the event of any discrepancies in words, accounts, figures, or the like between this report and the original, the original Japanese version shall govern.

AGENDA

■ Financial Results of 2015/3

■ Plan of 2016/3

■ ROHM's Strategy

1. Market Reform
2. Product Reform
3. Structural Reform

■ CAPEX

■ Return to Shareholders

■ ICs Business Strategy

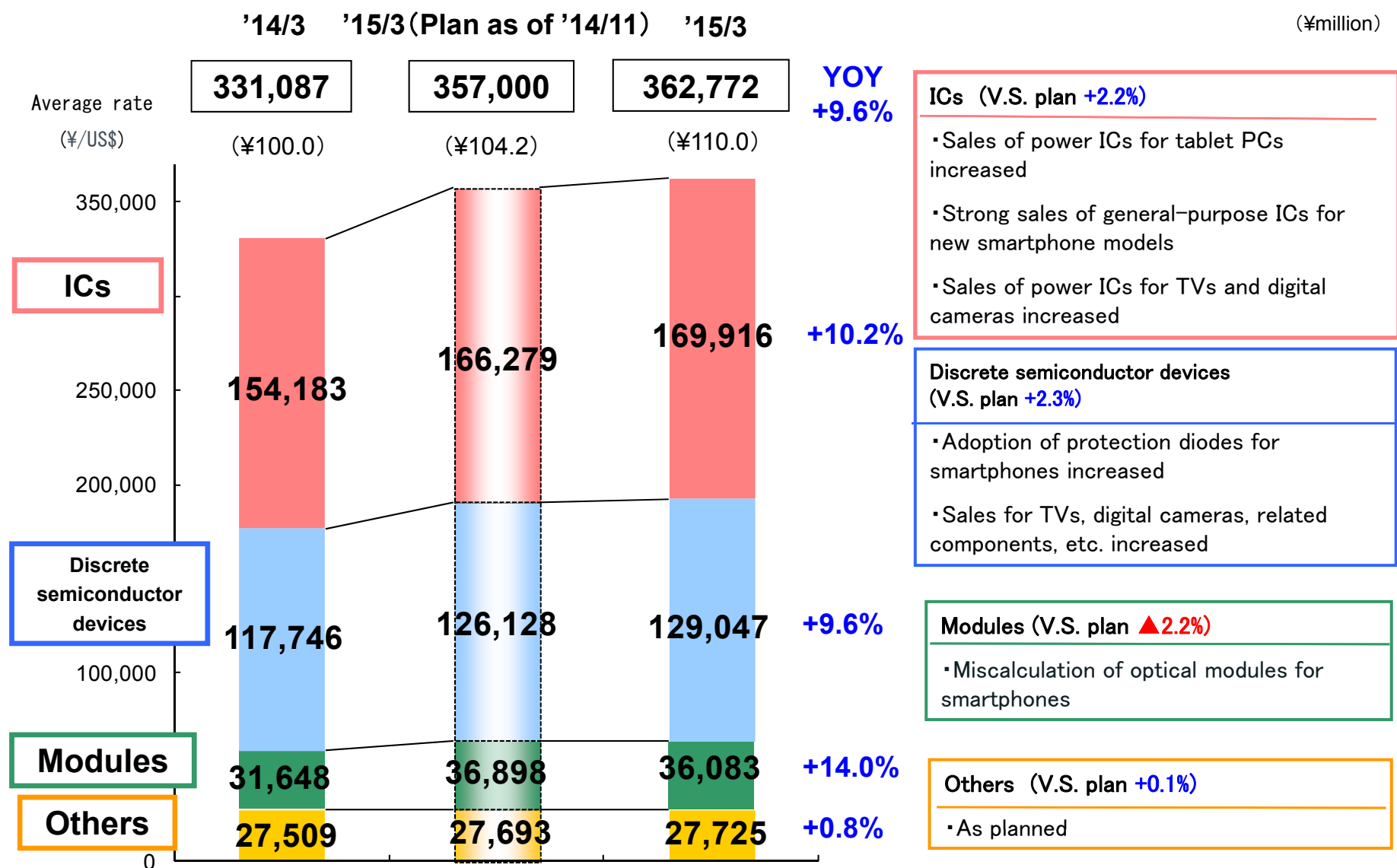
■ Discrete Semiconductor Devices・Modules Business Strategy

Financial Results of 2015/3 (YOY)

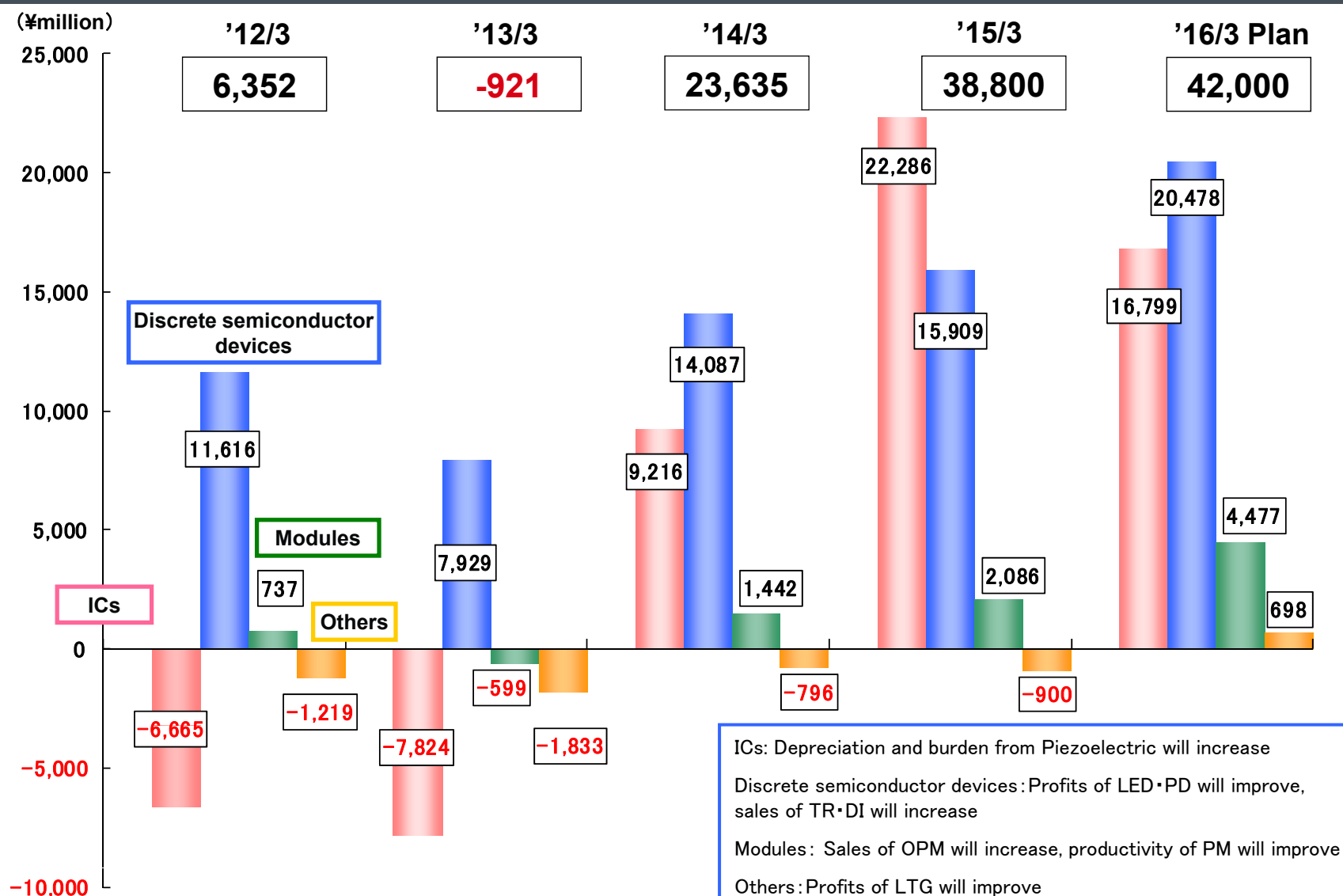
(¥million)

	'15/3	'14/3	Amount of increase	YOY
Sales	362,772	331,087	+31,685	+9.6%
Operating income	38,800	23,635	+15,165	+64.2%
(Ratio)	(10.7%)	(7.1%)	—	—
Ordinary income	59,218	35,915	+23,303	+64.9%
(Ratio)	(16.3%)	(10.8%)	—	—
Net income	45,296	32,091	+13,205	+41.1%
(Ratio)	(12.5%)	(9.7%)	—	—
EBITDA	73,267	49,194	+24,073	+48.9%
(Ratio)	(20.2%)	(14.9%)	—	—
Average rate (¥/US\$)	(110.03)	(100.00)		

Sales by Segment of 2015/3 (YOY)



Trend of Profits by Segment



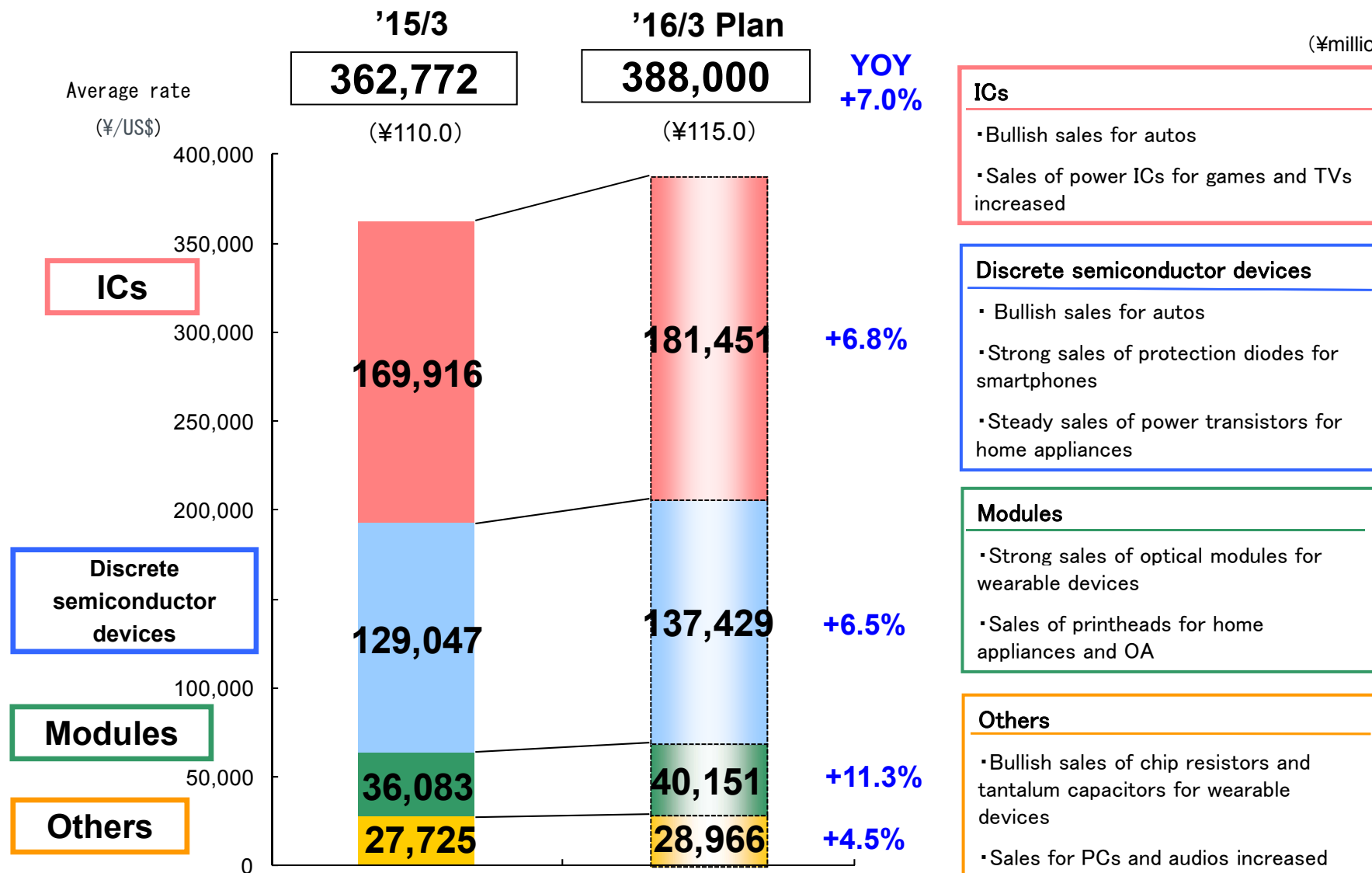
Plan of 2016/3 (YOY)

(¥million)

	'15/3		'16/3 Plan		
	Amount	YOY	Amount	Amount of increase	YOY
Sales	362,772	+9.6%	388,000	+25,228	+7.0%
Operating income	38,800	+64.2%	42,000	+3,200	+8.2%
(Ratio)	(10.7%)	—	(10.8%)	—	—
Ordinary income	59,218	+64.9%	40,000	▲ 19,218	▲ 32.5%
(Ratio)	(16.3%)	—	(10.3%)	—	—
Net income	45,296	+41.1%	30,000	▲ 15,296	▲ 33.8%
(Ratio)	(12.5%)	—	(7.7%)	—	—
EBITDA	73,267	+48.9%	86,800	+13,533	+18.5%
(Ratio)	(20.2%)	—	(22.4%)	—	—
Average rate (¥/US\$)	(110.03)		(115.00)		

Plan of Sales by Segment (YOY)

(¥million)



1. Market Reform

- Focusing on the auto market
- Developing the industrial market
- Increasing share of overseas customers

2. Product Reform

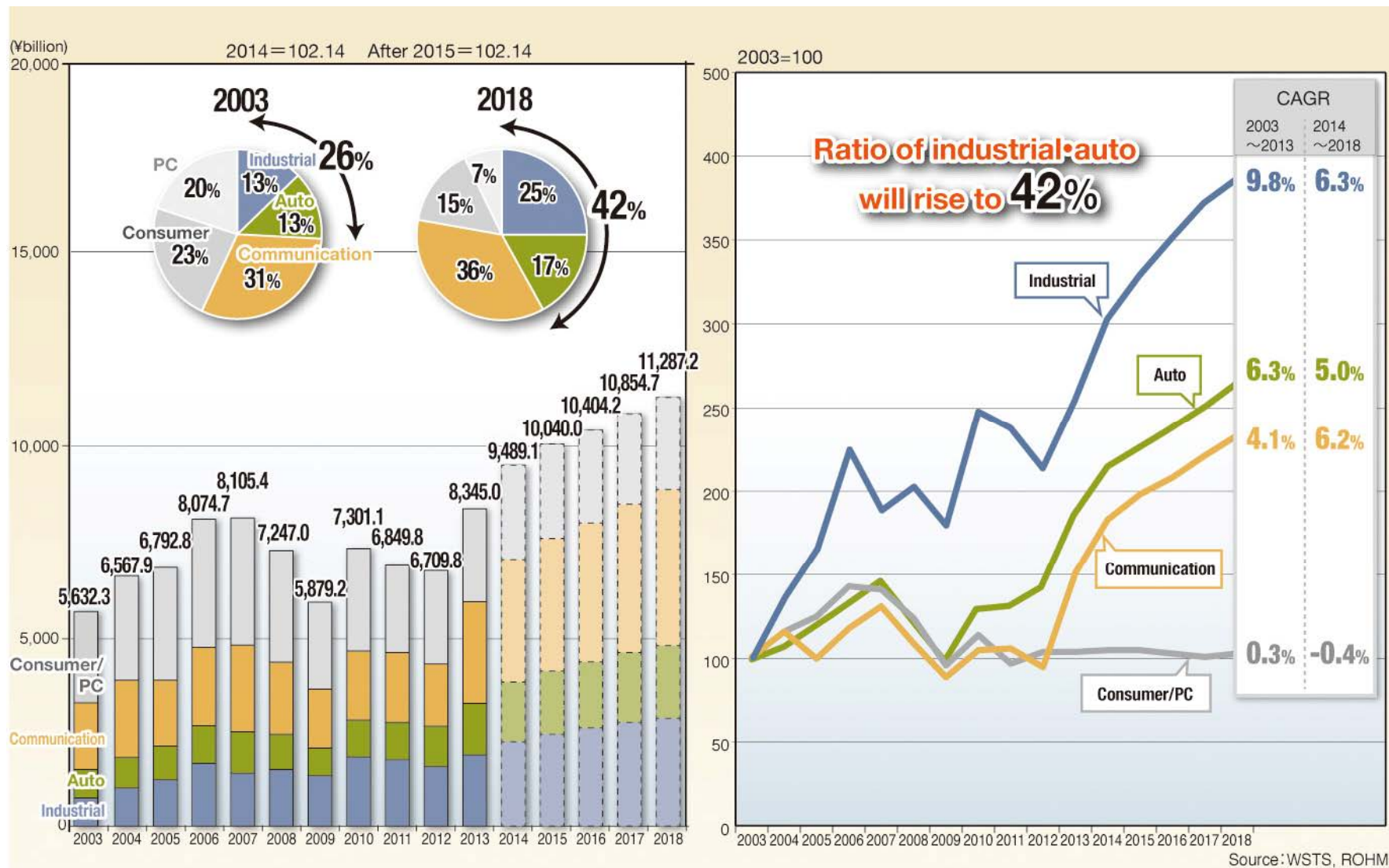
- Aiming to be the world's No.1 in analog power
- Focusing on the four growth engines
- Becoming a significant player in the IT field by microminiature devices

3. Structural Reform

- Thoroughly enhancing RPS (ROHM Production System)
- Investing to strengthen our mass production system for a larger capacity

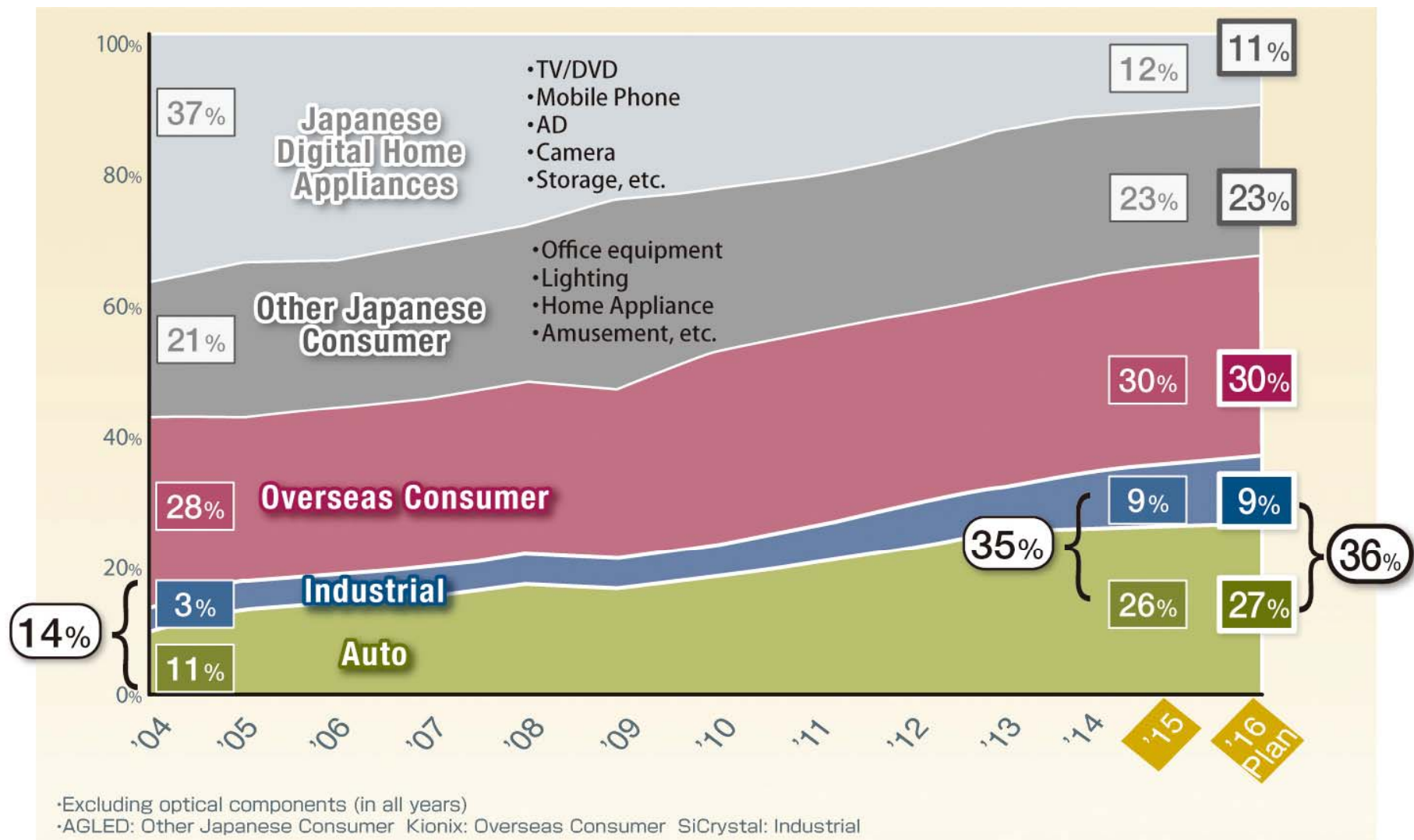
ROHM's Strategy 1.Market Reform

①Changes in Demand



ROHM's Strategy 1. Market Reform

② 13 Years Trend of Sales Ratio by Market



ROHM's Strategy 2.Product Reform

①Aiming to be the World's No.1 in Analog Power

Serving high level needs in the auto and industrial market by enhancing ROHM's strengths

**Responding
to
demands**

**Well-experienced
analog engineers**

- Power management
- Linear control
- Sensor control
- Motor control
- Audio
- Wireless technology

**One-stop
shopping**

Providing a wide range of products from world's smallest discrete semiconductor devices to highly efficient power devices

**Assuring
reliability**

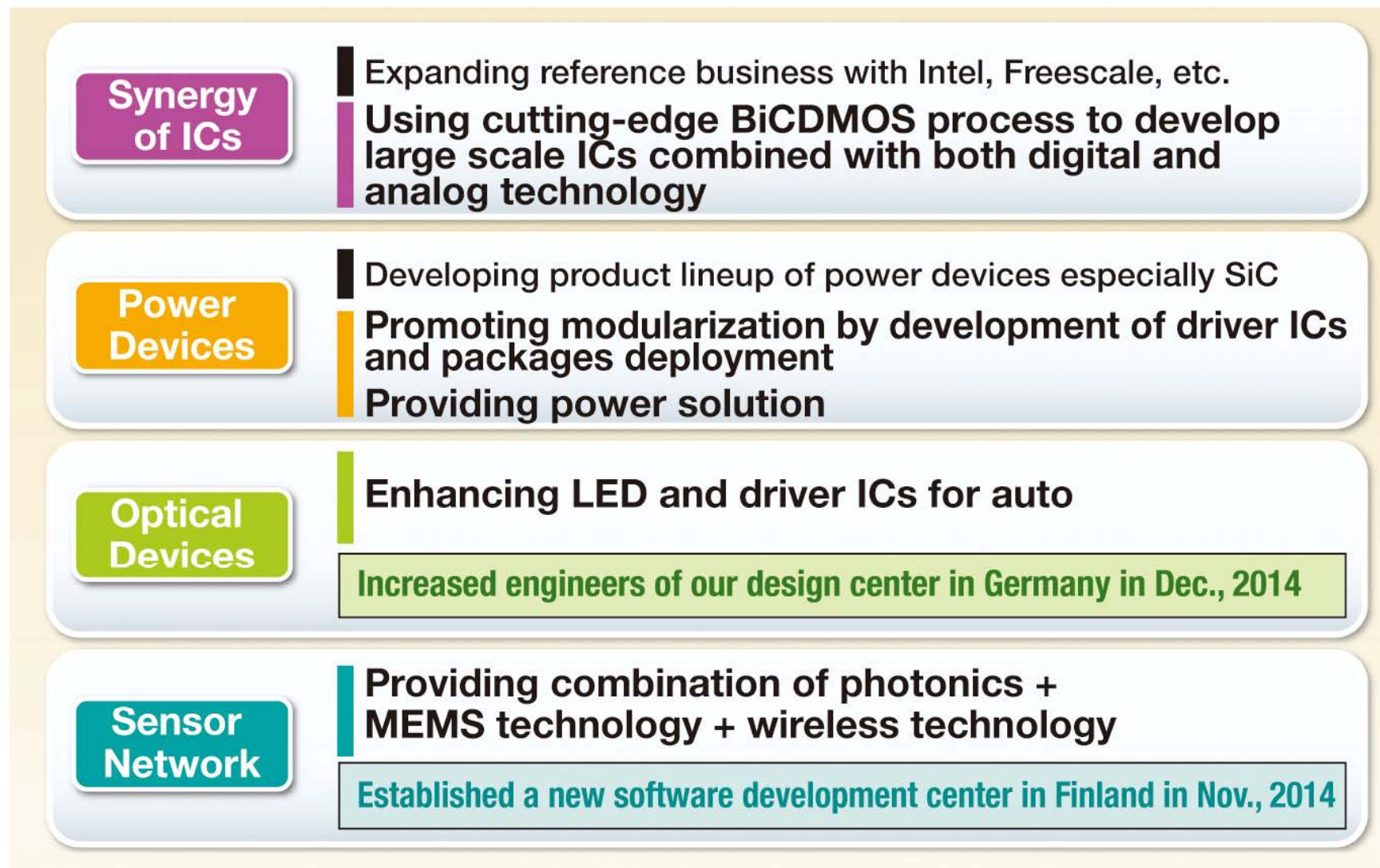
**Corporate culture:
Quality is
our first priority**

**Vertically integrated
process**

- Traceability
 - Just in time
 - Characteristic process development
- 【 World's No.1 BiCDMOS 0.13μm
World's cutting-edge SiC 6inch wafer 】

ROHM's Strategy 2.Product Reform

②Progress of the Four Growth Product Categories



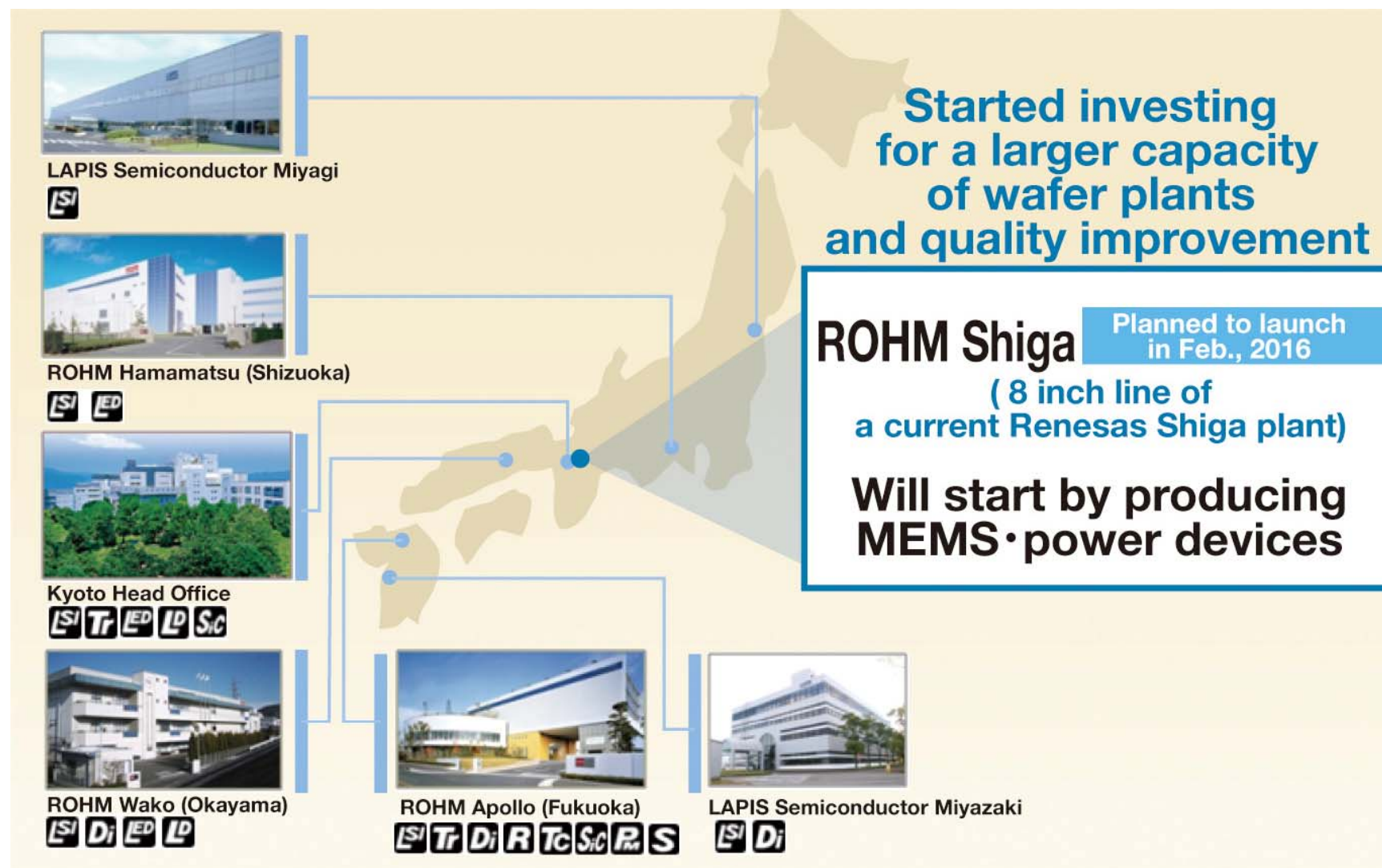
ROHM's Strategy 3. Structural Reform

① Thoroughly Enhancing RPS (ROHM Production System)



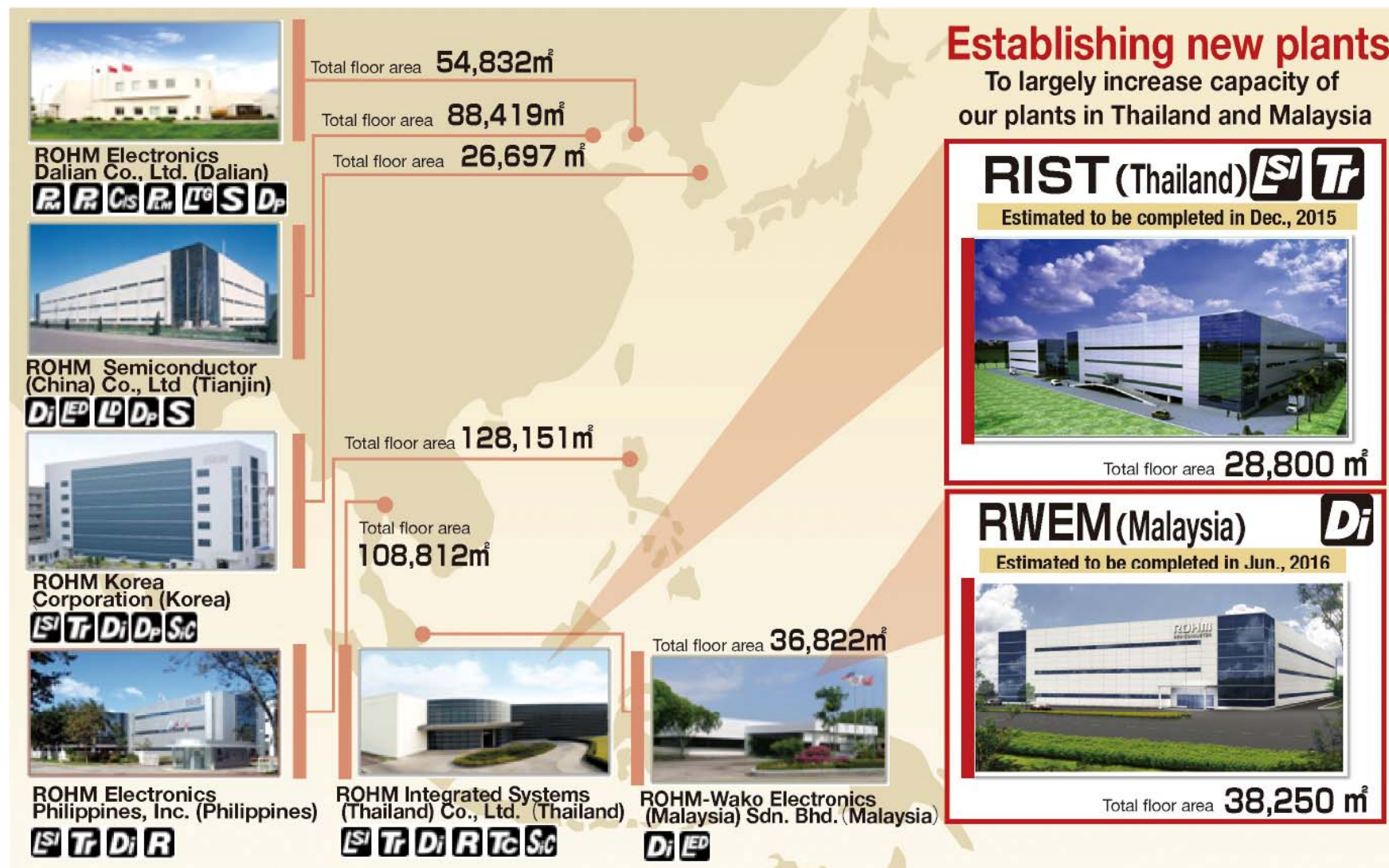
ROHM's Strategy 3.Structural Reform

② Investing for a Larger Capacity (Front-end Process=Wafer Plant)

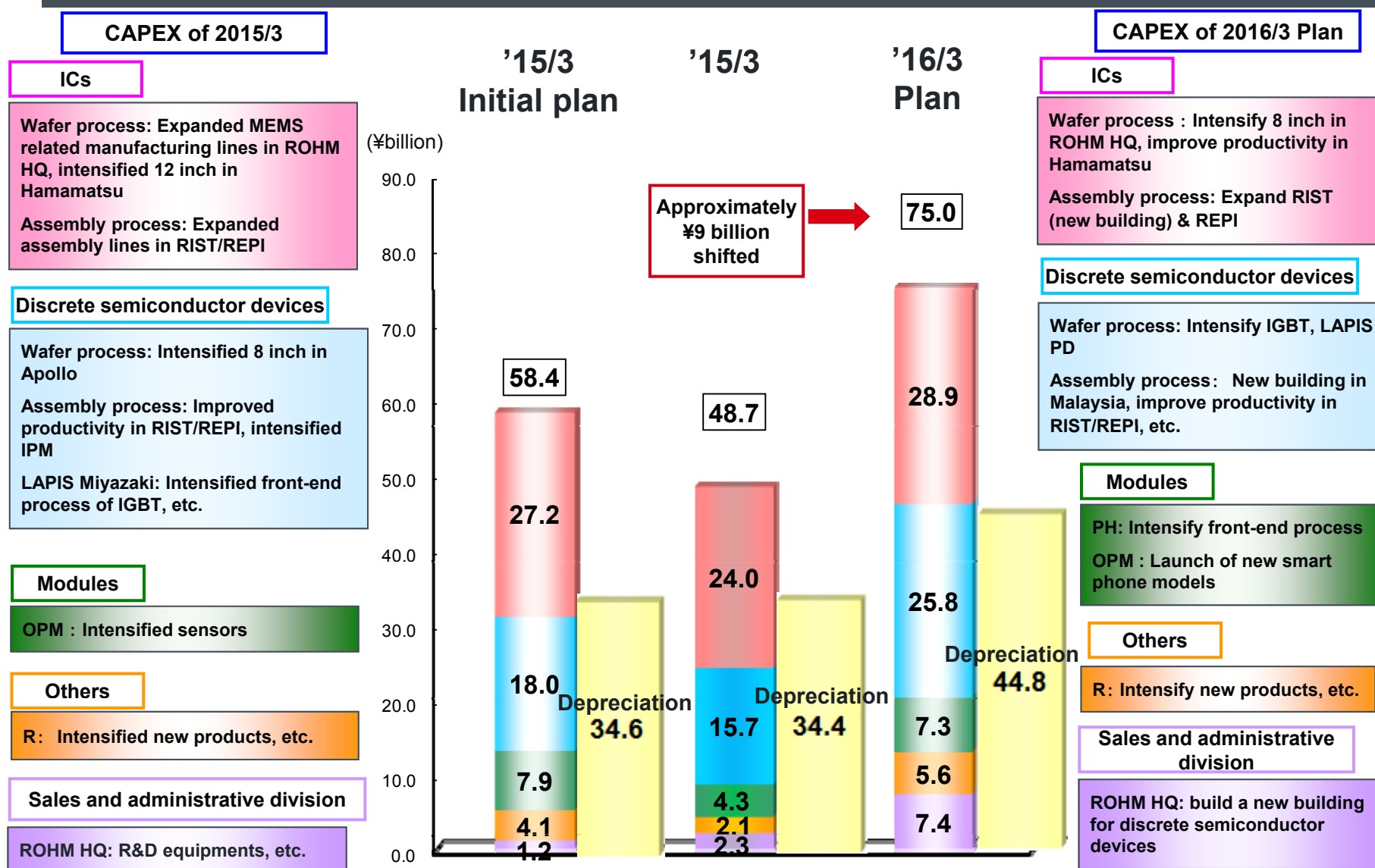


ROHM's Strategy 3.Structural Reform

③ Investing for a Larger Capacity (Back-end Process=Assembly Plant)



CAPEX -Comparison by Segments-



CAPEX -Comparison by Objectives-

CAPEX will be 1.5 times higher than 2015/3

Enforcing our supply system for strong demand and launch of mass production in new fields

Wafer process

<Launch of ROHM Shiga>

- To become a major plant of IGBT
- To start production of piezoelectric MEMS

Assembly process

- Building new plants in Thailand (ICs) and Malaysia (discrete semiconductor devices) and expanding capacity
- Renewing old equipment

(¥billion)

	Total	Capacity	Land·building	New products	Quality	Others
'16/3 Plan	75.0	33.3	16.0	11.4	7.9	6.4
Ratio	100%	44%	21%	15%	11%	9%

Japan/Overseas Ratio	'15/3	'16/3
Japan	52%	58%
Overseas	48%	42%
Total	100%	100%

Return to Shareholders Policy

Measures to improve corporate value

- We will continue to improve our corporate value by promoting “market reform”, “product reform” and “structural reform”
- Aggressively looking for M&A and alliance opportunities by taking advantage of our strong financial ground

Return to Shareholders Policy

New policy

- We will return 100% of our free cash flow to the stock market for 3 years (2015/3-2017/3) .



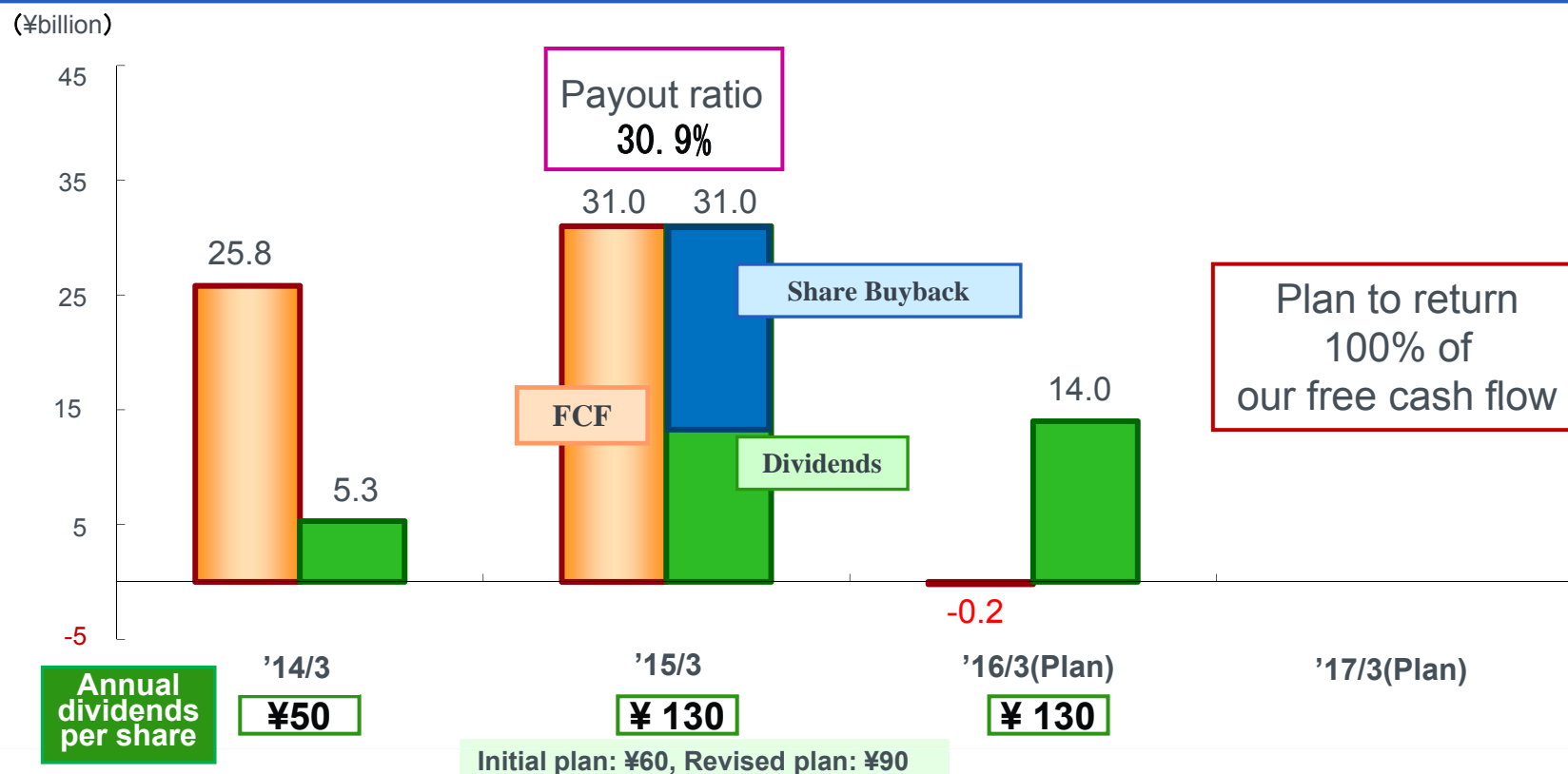
Existing policy

- We will make efforts to maintain stable dividends by aiming for consolidated payout ratio of around 30% .

Trend of Our Return to Shareholders

Return to Shareholders Measures

- ① 15/3 Dividend per share: ¥130, 16/3 plan: ¥130
- ② We will purchase ¥17 billion of our own shares as an additional return to shareholders (starting in May, 2015)



ICs Business Strategy

- ① Started mass production of BiCDMOS process 0.13μm analog ICs
Establishing analog IC technology base for autos and industrial
Ensuring high quality and performance of our products enabled by vertical integration to achieve competitive edge
- ② Aggressive investment and innovation of manufacturing lines for long term stable supply and higher quality
=Reestablishing RPS and upgrading our products to match auto quality=

③ Our major R&D themes

Auto	Expanding our product lineup to power train and safety device by gaining customers' trust in the global market
Reference business	Enhancing product lineup and entering the auto and industrial markets
Home appliance	Expanding market share of high-voltage motor drivers and power ICs in emerging countries
IoT	Entering the market with sensors and communication devices enabled by ROHM Group's synergy

ICs Business for Auto

Under development for 2018 models

Infotainment

Acquired stable share in Japan and overseas

Power supply•LED driver for clusters

Car audio•navigation system

In-car network
(Driver power supply for LIN)

Back monitor camera system

Direction•state control sensor

Beamforming directional microphone

Communication IC for panels

Power IC for panels

Capacitive touch switch

Resistance touch switch



Car body

Adopted by Japanese and a few overseas manufacturers

Air conditioners

Door•window control

Keyless entry

LED lamp control

LED driver for headlamp

Multiple interface IC

Communication IC

Dot matrix driver

Seat fan motor driver

LED headlight cooling fan



Power train

Begun to be adopted by Japanese manufacturers

Engine control•control sensor

Transmission

Throttle control

HEV, EV, FCV

Secondary battery control technology

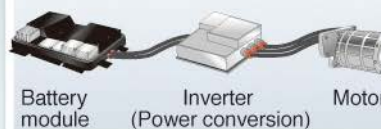
Motor•inverter technology

Multiple interface IC

Isolated gate driver

Smart switch

Temperature monitor



Safety device

Under mass production for Japanese manufacturers

Electric power steering (EPS)

Suspension control

Antiskid brake
(Accelerometer•gyro sensor)

ABS
(Revolution control)

Anti-slip control
(Accelerometer)

Tire pressure
(Pressure sensor)

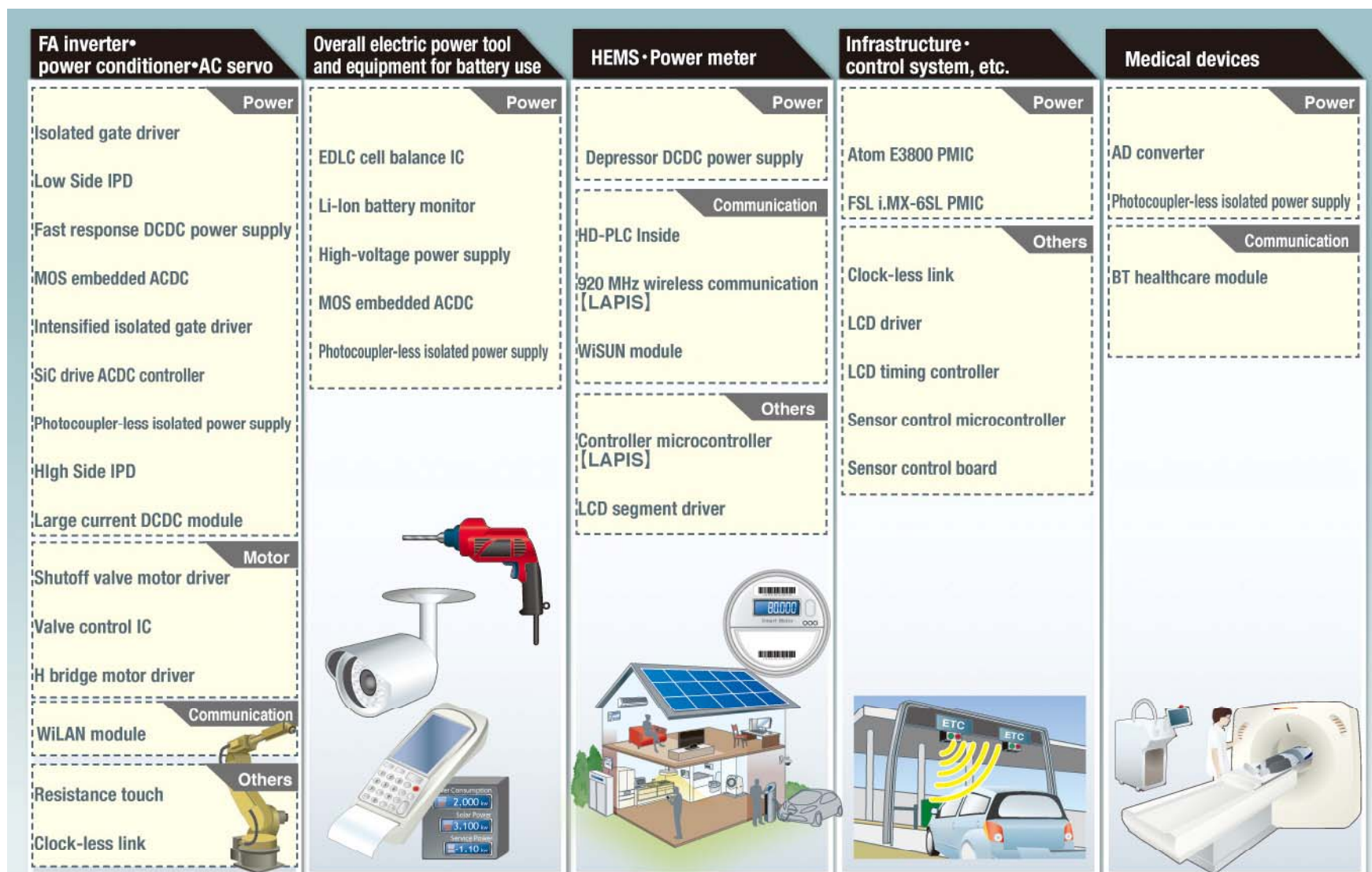
Environment surveillance

Ultrasonic detecting sensor

Auto camera power supply



ICs Business for Industrial



Discrete Semiconductor Devices/Modules Business Strategy

① Enhancing development and deployment of products for the power market

- Cutting-edge SiC power device products
- Wide range of power products from resistors to SiC

② Acquiring No.1 worldwide market share of small signal semiconductor devices

- Enhancing product lineup of ROHM's microminiature devices "RAS MID™" series
- Continuing investment to switch to highly efficient manufacturing lines

③ Sustaining efforts targeting a wide range of markets for further future growth

- Enhancing product lineup for growing markets
- Strengthening reference business
- Development and deployment of small-sized communication modules for IoT

④ Development and production strategy

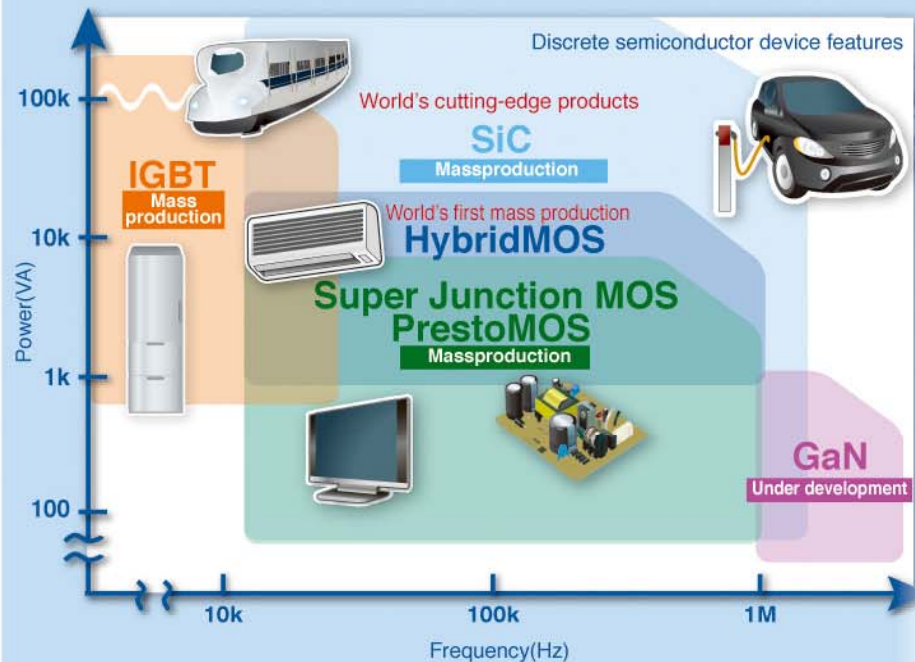
- Developing and producing competitive products

Discrete Semiconductor Devices/Modules Business Strategy

- Power Strategy -

Developing a wide range of products featuring advantages of Si, SiC, GaN

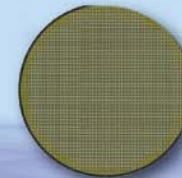
Product lineup of power devices mainly SiC



HybridMOS : Realizing low loss throughout all areas from low to high load
(Covers high power areas that PrestoMOS cannot withstand)

PrestoMOS : Contributing to energy saving through reducing loss by high-speed trr

Wafer business



Power discrete semiconductors



Passive components



IC control technology

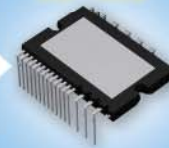


Control technology + Module technology

IPM

PM

Realizing low loss and large currents
by double trench MOS embedded



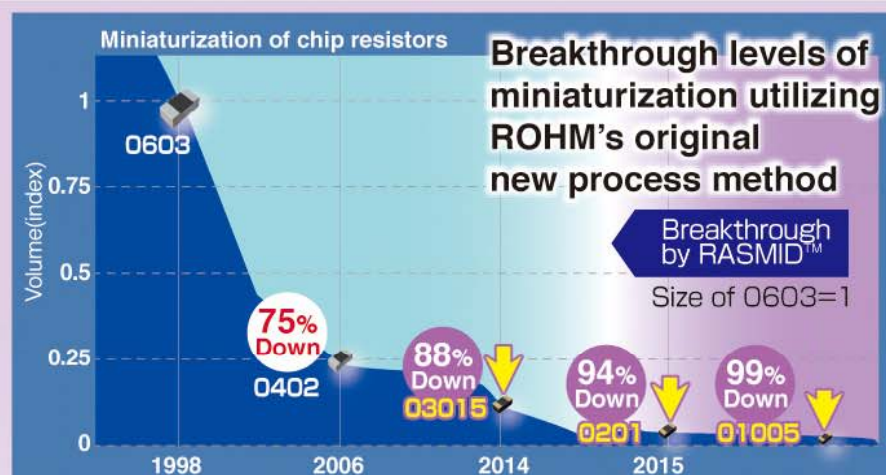
(1200V/180A)



(~1200V/300A)

Discrete Semiconductor Devices/Modules Business Strategy

- Small Signal Strategy -



Order situation (2015 estimate)

Planned to be adopted by a chipset manufacturer for a major mobile phone

Being adopted

0603 SBD For smart phones

0603 TVS For smart phones

03015 R For measuring equipments

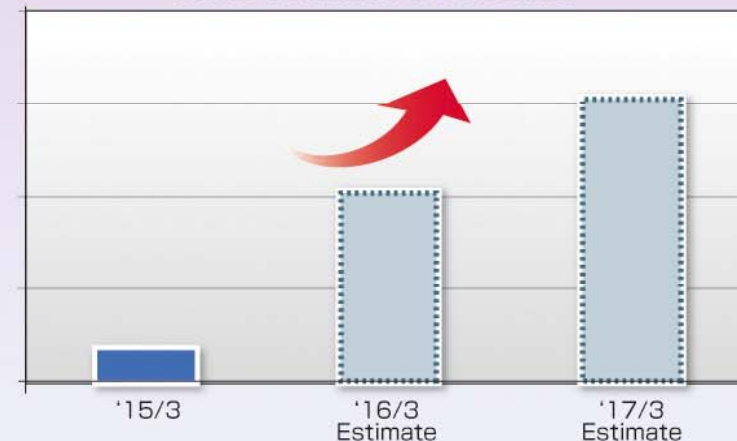
Increasing lineup and improving chip features

		~2013	2014	2015	2016
Resistors	Low TCR, Low noise type	03015		0201	01005
Diodes	Schottky barrier diode	0603	0402		
	Zener diode (simplex)	0603	0402		
	Zener diode (bidirectional)		0603	0402	
	TVS diode (general-purpose)	0603		0402	
	TVS diode (low volume)		0603	0402	
Filter	RC filter			0603	
	LC filter			0603	
Chip fuse			1005		

New Lineup

Sample distribution of LCR filters from 2015/3 2H

Sales estimate of RASPID™



Discrete Semiconductor Devices/Modules Business Strategy

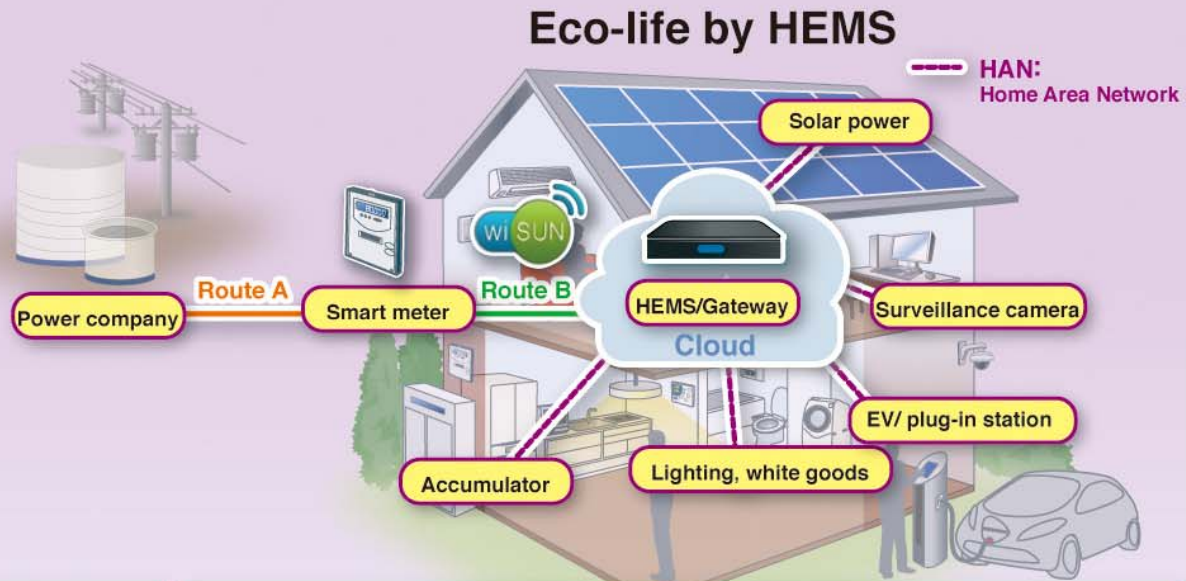
- Continuing Actions for a Wide Range of Markets -

Features of Wi-SUN

Accessible
without electricity



Suited for HEMS



LAPIS
SEMICONDUCTOR

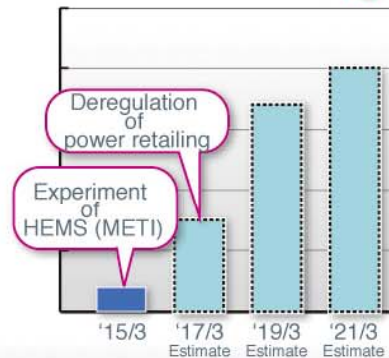


BP35A1

- Only one to be registered as CTBU* in the Wi-SUN Alliance
- Only Japanese IC manufacturer to produce communication IC for Wi-SUN

*Certified Test Bed Unit

ROHM's sales target



Spread of Wi-SUN

(Wireless Smart Utility Network)

- International wireless communication standard initiated by Japan
- Long distance and low power consumption by 920MHz wireless
- Adopted in route B of smart meters

Discrete Semiconductor Devices/Modules Business Strategy

- Auto -

From “small signal devices” to “power devices”

**Aiming to expand sales
by car body•power train•safety device!**

Power device

Infotainment

- Small signal** **Tr** Small signal MOSFET
Small signal bipolar transistor
Digital transistor
- Di** Switching diode
Schottky diode
Zener diode
- R** Square shape resistor
Shunt resistor

Car body

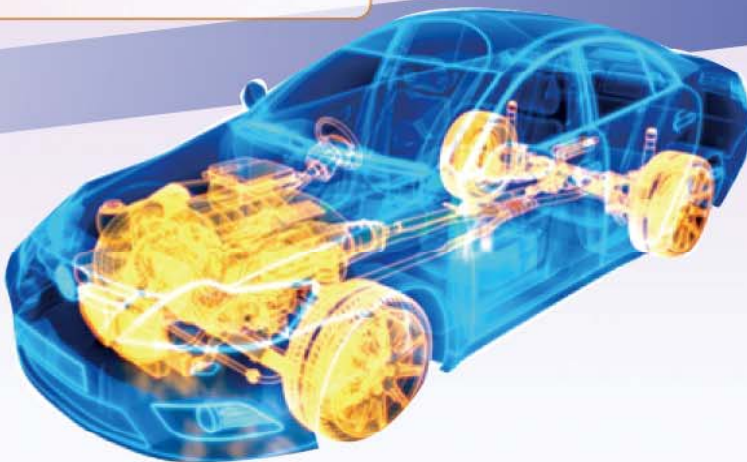
- Tr** **Power MOSFET**
- Small signal** **Tr** Small signal MOSFET
Small signal bipolar transistor
Digital transistor
- Di** **Ultra low Ir schottky diode**
Fast recovery diode
- Small signal** **Di** Switching diode
Schottky diode
Zener diode
- R** Square shape resistor
Shunt resistor

Power train

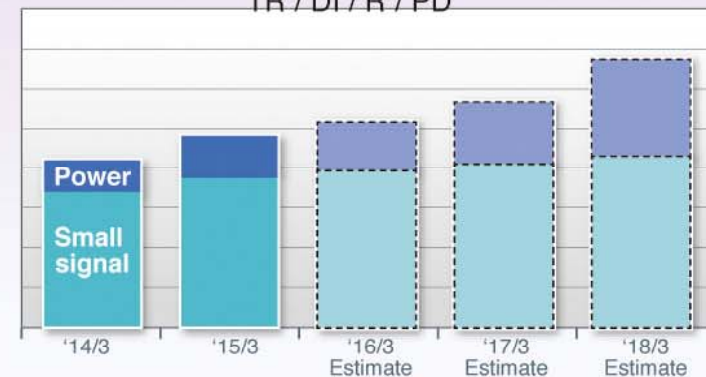
- Tr** **Power MOSFET**
- SiC** **SiC schottky diode**
SiC MOSFET
- IGBT** **IGBT Module**
- Di** **Ultra low Ir schottky diode**
Fast recovery diode
- R** Square shape resistor
Power shunt resistor

Safety device

- Tr** **Power MOSFET**
- Small signal** **Tr** Small signal MOSFET
Small signal bipolar transistor
Digital transistor
- Di** **Ultra low Ir schottky diode**
Fast recovery diode
- Small signal** **Di** Switching diode
Schottky diode
Zener diode
- R** Square shape resistor
Power shunt resistor



Sales estimate of autos
TR / DI / R / PD



Note Regarding Future Forecasts

The forecast statements in this report are based on information currently available and deemed by ROHM Group as reasonable, and therefore, are not intended to guarantee to be achieved by ROHM Group, and actual results may differ materially by various factors.

ROHM Group does not bear responsibility to update and disclose any future forecasts in this report.

Also, since the purpose of this report is to provide an outline of business performance, many figures are shown in unit of a billion yen, therefore, totals and differences of figures may appear inaccurate. Please refer to our Financial Report for detailed figures.

